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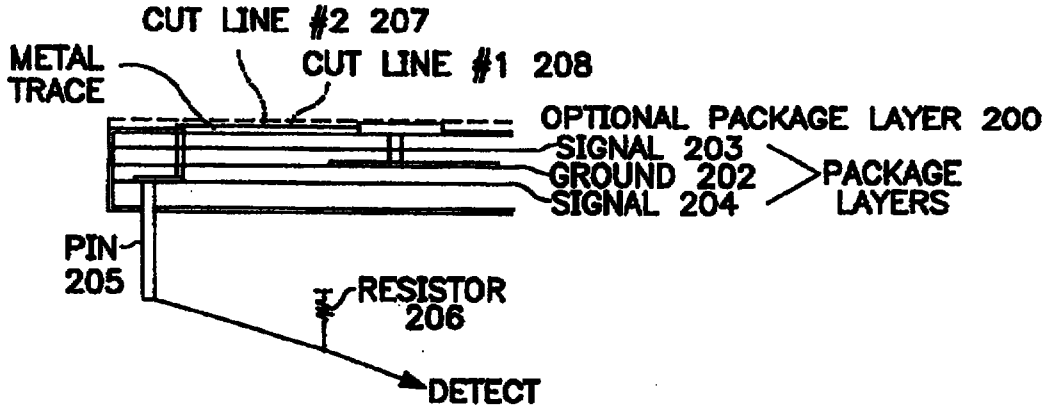
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(54) Title: AN INTEGRATED CIRCUIT PACKAGE WITH PERMANENT IDENTIFICATION OF DEVICE CHARACTERISTICS AND METHOD FOR ADDING THE SAME



(57) Abstract

An integrated circuit (IC) device package that includes permanent identification (207, 208) regarding the device characteristics, wherein the permanent identification (207, 208) are at or below the surface (200) of the package and may indicate the operating frequency of an IC die within the package, as well as voltage requirements, etc.